



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-09-07
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STH315N10F7-6	R2(4*OD0KA52	A	SH1A	2015-09-07
Amount	UoM	Unit type	ST ECOPACK Grade	
1380.00	mg	Each	ECOPACK® 1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DIP	10.2 - 9.15 - 4.5	6	Through-hole	
Comment	Package: H2PAK 6 Leads			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-15th June 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	R2(4*ODOKA52					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die (s)	Other inorganic materials	20.606	mg	supplier	die	Silicon (Si)	7440-21-3		19.011	mg	922603	13778
				supplier	metallization	Copper (Cu)	7440-50-8		0.941	mg	45662	682
				supplier	metallization	Titanium (Ti)	7440-32-6		0.383	mg	18585	278
				supplier	metallization	Tungsten (W)	7440-33-7		0.006	mg	291	4
				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.09	mg	4367	65
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.009	mg	437	7
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.112	mg	5435	81
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.008	mg	388	6
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.046	mg	2232	33
				supplier	alloy	Copper (Cu)	7440-50-8		604.872	mg	996718	438313
Leadframe	Copper & its alloys	606.864	mg	supplier	alloy	Iron (Fe)	7439-89-6		0.279	mg	460	202
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.509	mg	839	369
				supplier	metallization	Nickel (Ni)	7440-02-0		1.197	mg	1972	867
				supplier	metallization	Phosphorus (P)	12185-10-3		0.007	mg	12	5
Soft solder	Solder	12.715	mg	JIG R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	12.143	mg	955014	8799
				supplier	solder	Silver (Ag)	7440-22-4		0.318	mg	25010	230
				supplier	solder	Tin (Sn)	7440-31-5		0.254	mg	19976	184
Bonding wire	Other inorganic materials	16.943	mg	supplier	wire	Aluminium (Al)	7429-90-5		16.941	mg	999882	12276
				supplier	wire	Magnesium (Mg)	7439-95-4		0.002	mg	118	1
Encapsulation	Other inorganic materials	720.782	mg	supplier	mold compound	Silica, vitreous	60676-86-0		576.625	mg	799999	417844
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		50.454	mg	69999	36561
				supplier	mold compound	Phenol resin	9003-35-4		28.832	mg	40001	20893
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		43.247	mg	60000	31338
				supplier	mold compound	Antimony Trioxide	1309-64-4		8.65	mg	12001	6268
				JIG I	mold compound	Brominated Epoxy Resin	40039-93-8		10.812	mg	15000	7835
				supplier	mold compound	Carbon Black	1333-86-4		2.162	mg	3000	1567
Connections coating	Solder	2.09	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		2.09	mg	1000000	1514